NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only.
   Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.
NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see the QFN/SON PCB application note in literature No. SLUA271 (www.ti.com/lit/slua271).
NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
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